

ABSTRACT

The present invention provides a magazine for a semiconductor package on which semiconductor strips of various sizes can be loaded
5 without increasing the manufacturing cost and time period of manufacture, and which can prevent inferiority of semiconductor manufacture due to static electricity. In order to achieve these objects, bodies having a plurality of guides on one side of each for loading semiconductor strips and upper and lower plates which determine the width of semiconductor strips are
10 separately manufactured, and then said bodies and said upper and lower plates are connected by connection means to form a magazine for a semiconductor package for loading semiconductor strips so as to transfer them in a semiconductor process. Since the magazine of the present invention can be loaded with semiconductor strips of various sizes without
15 manufacturing a separate magazine, its manufacturing cost can be reduced and its manufacturing time period can be shortened. In addition, the yield of the semiconductor manufacturing process can be improved, since electrical damage to semiconductor chips can be prevented by forming a magazine with a conductive engineering plastic.

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